



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C103JBFNFNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 10nF, 50V, ±5%, C0G, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>103</u> <u>J</u> <u>B</u> <u>F</u> <u>N</u> <u>F</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | |
|-----|---------------|---------------------------------------|-------------------|-------------------------------|
| 2 | Size | 0805 (inch code) | L: 2.0 ± 0.1 mm | W: 1.25 ± 0.1 mm |
| | | | | |
| 3 | Dielectric | C0G | 8 Inner electrode | Ni |
| 4 | Capacitance | 10 nF | Termination | Cu |
| (5) | Capacitance | ±5 % | Plating | Sn 100% (Pb Free) |
| | tolerance | | Product | Product for POWER application |
| 6 | Rated Voltage | 50 V | Special | Reserved for future use |
| 7 | Thickness | 1.25 ± 0.1 mm | ① Packaging | Embossed Type,7"reel(2,000ea) |

B. Samsung Reliability Test and Judgement condition

| | Performance | Test condition | |
|-------------------|---|---------------------------------------|--|
| Capacitance | Within specified tolerance | 1kl/z±10% 0.5~5Vrms | |
| Q | 1000 min | | |
| Insulation | More than 500Mohm⋅μΓ | Rated Voltage 60~120 sec. | |
| Resistance | | | |
| Appearance | No abnormal exterior appearance | Visual inspection | |
| Withstanding | No dielectric breakdown or | 300% of the rated voltage | |
| Voltage | mechanical breakdown | | |
| Temperature | COG | | |
| Characteristics | (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃) | | |
| Adhesive Strength | No peeling shall be occur on the | 500g·F, for 10±1 sec. | |
| of Termination | terminal electrode | | |
| Bending Strength | Capacitance change: within ±5% | Bending to the limit (1mm) | |
| | | with 1.0mm/sec. | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | |
| | is to be soldered newly | 245±5℃, 3±0.3sec. | |
| | | (preheating : 80~120 ℃ for 10~30sec.) | |
| Resistance to | Capacitance change: within ±2.5% | Solder pot : 270±5℃, 10±1sec. | |
| Soldering heat | Tan δ, IR : initial spec. | | |
| | | | |

| | Performance | Test condition |
|------------------|----------------------------------|-------------------------------------|
| Vibration Test | Capacitance change: within ±2.5% | Amplitude : 1.5mm |
| | Tan δ, IR : initial spec. | From 10Hz to 55Hz (return : 1min.) |
| | | 2hours × 3 direction (x, y, z) |
| Moisture | Capacitance change: within ±7.5% | With rated voltage |
| Resistance | Q: 200 min | 40±2℃, 90~95%RH, 500 +12/-0 hours |
| | IR : More than 25MΩ·μF | |
| | | |
| High Temperature | Capacitance change: within ±3% | With 200% of the rated voltage |
| Resistance | Q: 350 min | Max. operating temperature |
| | IR : More than 50MΩ·μF | 1000+48/-0 hours |
| | | |
| Temperature | Capacitance change: within ±2.5% | 1 cycle condition |
| Cycling | Tan δ, IR : initial spec. | Min. operating temperature → 25 °C |
| | | → Max. operating temperature → 25°C |
| | | |
| | | 5 cycles test |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.